What is claimed is:

1. A system comprising:

a defect review tool, wherein the defect review tool includes:

a stage configured to clamp a wafer; and

an image generation system configured to generate an image of a layer of a surface of the wafer; and

a controller configured to communicate with the defect review tool, wherein the controller is configured to:

generate a coordinate system for a current layer and generate a corresponding coordinate system for a previous layer, wherein the coordinate system for the current layer and the coordinate system for the previous layer are each one of a grid-based system, a polar system, or three-dimensional coordinate system that uses matrices;

align a design file for the current layer of the wafer to an image of the current layer with the coordinate system for the current layer;

align a design file for the previous layer of the wafer to the design file for the current layer with the coordinate system for the previous layer, wherein the previous layer is formed prior to the current layer; and

identify a region of the image of the current layer based on a coordinate of a defect in the previous layer, wherein the region corresponds to the coordinate of the defect in the previous layer.

2. The system of claim **1**, wherein the controller includes a processor, a storage device in electronic communication with the processor, and a communication port in electronic communication with the processor.

3. The system of claim **1**, wherein at least one die corner of the wafer is marked.

4. The system of claim **3**, wherein the controller is further configured to adjust the die corners to a die coordinate system for the previous layer after aligning the design file for the previous layer.

5. The system of claim **1**, wherein the controller is further configured to deskew the image of the current layer.

6. The system of claim **1**, wherein the image of the current layer is a scanning electron microscope image.

7. The system of claim **1**, wherein the controller is further configured to align an image of the previous layer to at least one of the design file for the previous layer or the design file for the current layer.

8. The system of claim **1**, wherein the image generation system is configured to use at least one of an electron beam, a broad band plasma, or a laser.

9. The system of claim **1**, wherein one of the coordinate system for the current layer and the coordinate system for the previous layer is the grid-based system, and wherein the grid-based system uses an X-Y coordinate system.

10. A method comprising:

aligning a wafer in a defect review tool using a stage;

marking at least one die corner of the wafer;

generating a coordinate system for a current layer and generating a corresponding coordinate system for a previous layer using the controller, wherein the coordinate system for the current layer and the coordinate system for the previous layer are each one of a grid-based system, a polar system, or three-dimensional coordinate system that uses matrices;

aligning using a controller a design file for the current layer of the wafer to an image of the current layer with the coordinate system for the current layer;

aligning using the controller a design file for the previous layer of the wafer to the design file for the current layer with the coordinate system for the previous layer, wherein the previous layer is formed prior to the current layer; and

identifying a region of the image of the current layer based on a coordinate of a defect in the previous layer using the controller, wherein the region corresponds to the coordinate of the defect in the previous layer.

11. The method of claim **10**, further comprising adjusting the die corners to a die coordinate system for the previous layer after aligning the design file for the previous layer.

12. The method of claim **10**, further comprising generating lots with defect site images of the current layer and the previous layer using the controller.

13. The method of claim **10**, further comprising deskewing the image of the current layer using the controller.

14. The method of claim **10**, wherein the image of the current layer is a scanning electron microscope image.

15. The method of claim **10**, further comprising aligning an image of the previous layer to at least one of the design file for the previous layer or the design file for the current layer.

16. The method of claim **10**, further comprising identifying, using the controller, the location of a defect in an image of the previous layer prior to identifying the region of the image of the current layer.

17. The method of claim **16**, further comprising aligning the image of the previous layer to the design file for the previous layer.

18. The method of claim **10**, wherein one of the coordinate system for the current layer and the coordinate system for the previous layer is the grid-based system, and wherein the grid-based system uses an X-Y coordinate system.